



[TC2] Next Generation Plasma Etching I	
Date / Time	July 26 (Thu.), 2018 / 13:20-15:00
Place	Room C (#114)
Session Chair(s)	Thorsten Lill (Lam Research Corp., USA) Alok Ranjan (Tokyo Electron, USA)

TC2-1 [Invited] 13:20-13:50

Some Aspects of Process Development in Plasma Etching

Nam Hun Kim

Adaptive Plasma Tech. Corp., Korea

TC2-2 13:50-14:10

Development of the Virtual Metrology Using a Plasma Information Variable (PI-VM) for Monitoring SiO₂ Etch Depth

Yunchang Jang, Hyun-Joon Roh, Sangwon Ryu, Ji-Won Kwon, and Gon-Ho Kim

Seoul Nat'l Univ., Korea

TC2-3 14:10-14:30

Withdrawn

TC2-4 [Invited] 14:30-15:00

Plasma and Feature Scale Models for Etching of High Aspect Ratio Silicon Structures in Pulsed Inductively Coupled Plasmas

Jason Kenney, Jun-Chieh Wang, Wei Tian, Shahid Rauf, Samaneh Sadighi, Phillip Stout, Vinay Vidyarthi,

Janny Guo, Kenneth Delfin, and Nicole Lundy

Applied Materials, Inc., USA